

MycoComposite 570

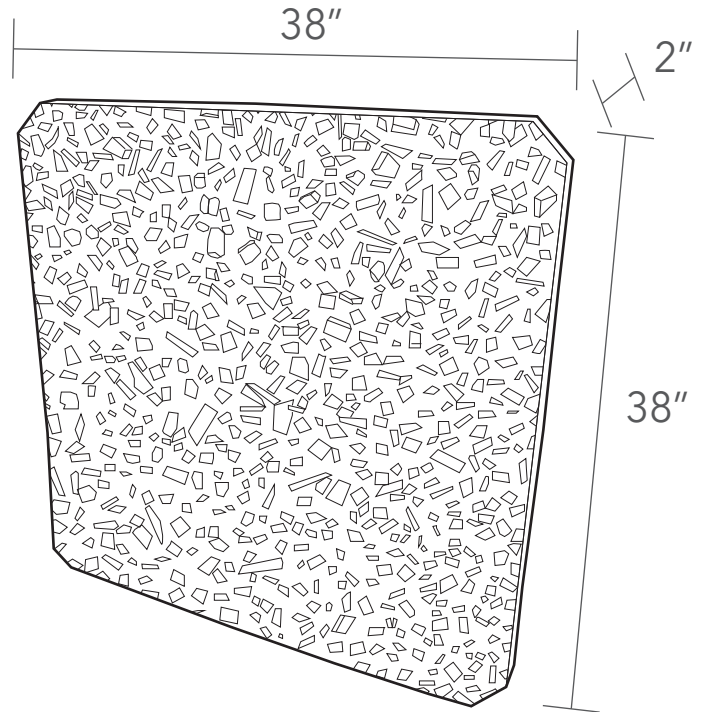
Aspen Chip Mycelium Panel

Description

The MycoComposite panels are the largest mycelium component panel available on the global market. MycoComposite 570 utilizes mycelium as the binding agent for the Aspen Chip substrate. The panels are pre-cut with surfaces ready for fabrication.

Ingredients

Aspen Chip	95%
Mycelium	5%



Material Properties

Density	Tension	Compression
12 lb/ft ³ 190 kg/m ³	6-20 psi 40-140 kPa	30-60 psi 210-410 kPa
Noise Reduction Coefficient	R-Value	Fire Rating
0.4	2.4 °Fft ² h/BTU	No Rating
Modulus of Elasticity	Flexural Strength	Flexural Modulus
500-610 psi 3400-4200 kPa	18-30 psi 120-210 kPa	1500-2300 psi 10000-16000 kPa

Potential Applications

Door Core
Furniture
Aquaculture
Wetland Remediation
Outdoor Layment
Heavy Blocking/Bracing

Suggested Finishes

Water-based Polyurethane
Beeswax
Milk Paint

